# MIMOTEL Thinning

- 2 thinning possibilities : 120 $\mu m$ and 50 $\mu m$ residual thickness

  - 120 $\mu m$ thinning:
    - done by CMP together with dicing
      - operation performed on wafer
        - no handling difficulty
          - can be done within a few weeks

  - 50 $\mu m$ thinning:
    - done in San Francisco Bay
      - may be done on individual sensors
        - handling/bonding delicate (?)
          - needs probably a few months

# Possible next steps

- **Available sets of sensors:**
  - *1st batch (2006) : diced sensors from 1 wafer of each epitaxial thickness*
  - *2nd batch (2007) : 1 undiced wafer of each epitaxial thickness*
    - $\longmapsto$ *under probe test (leakage current measurement of MIMO★-3L)*

- **2007 steps (proposal):**
  - *complete the probe tests of 2nd batch wafers ($\longmapsto$ feedback to AMS ...)*
  - *thin (and dice) one of these wafers to 120 $\mu m$*
    - $\longmapsto$ *which one ("14 $\mu m$" vs "20 $\mu m$" epi) ?*
  - *could be available for tests early Autumn*
    - $\longmapsto$ *could be mounted on the telescope in Octobre/Novembre ?*
  - *should beam test data be collected with these sensors in 2007 ?*

- **2008 steps (proposal):**
  - *thin individual sensors to 50 $\mu m$ (Autumn 2007 ?)*
  - *check that there are enough PCB copies $\longmapsto$ react in 2007 if needed*
  - *check that bonding and handling issues are under control  react in 2007 if needed*
  - *envisage mounting thinned sensors on telescope in Spring 2008 (?)*